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(54) Title: A METHOD OF MANUFACTURING A MEMS MICRO-MIRROR ASSEMBLY

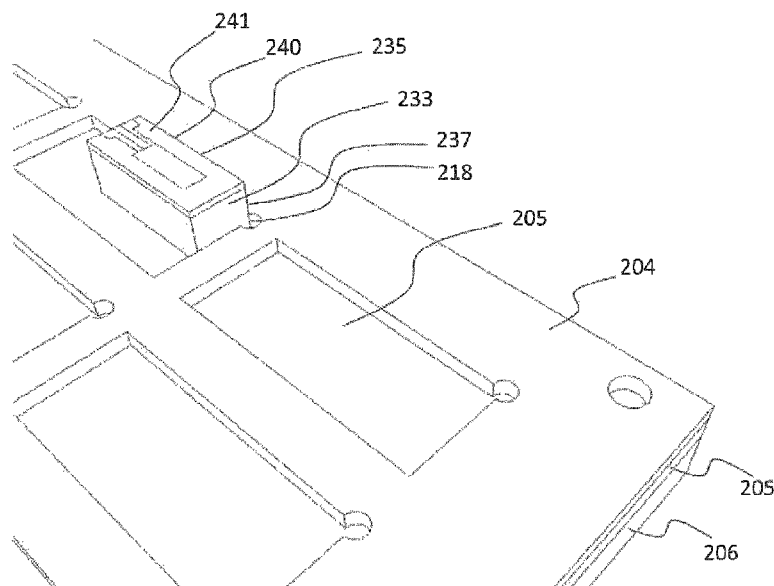


Fig. 4

(57) Abstract: According to the present invention there is provided a method of manufacturing a MEMS micro mirror assembly (250), comprising the step of mounting a PCB board (205) on a metallic plate (206), mounting a MEMS device (240) on the PCB board (205), wherein the MEMS device (240) comprises a MEMS die (241) and a magnet (230).



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